

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Zvi Or-Bach</td> <td>04/17/2013</td> </tr> <tr> <td>Brian Cronquist</td> <td>04/17/2013</td> </tr> <tr> <td>Deepak Sekar</td> <td>04/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	Zvi Or-Bach	04/17/2013	Brian Cronquist	04/17/2013	Deepak Sekar	04/18/2013		
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Deepak Sekar	04/18/2013										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>MonolithIC 3D Inc.</td> </tr> <tr> <td>Street Address:</td> <td>3555 Woodford Drive</td> </tr> <tr> <td>City:</td> <td>San Jose</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95124</td> </tr> </table>		Name:	MonolithIC 3D Inc.	Street Address:	3555 Woodford Drive	City:	San Jose	State/Country:	CALIFORNIA	Postal Code:	95124
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13864243</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13864243						
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Application Number:	13864243										
CORRESPONDENCE DATA											
Fax Number: <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Email: Brian@MonolithIC3D.com Correspondent Name: Brian Cronquist Address Line 1: 3555 Woodford Drive Address Line 4: San Jose, CALIFORNIA 95124											
ATTORNEY DOCKET NUMBER:	MONOLITHIC3D-HR10CON3										
NAME OF SUBMITTER:	Brian Cronquist										
Signature:	/bc/										
Date:	04/18/2013										
Total Attachments: 3 source=MonolithIC3D-HR10con3_Assignment_Zvi_s#page1.tif source=MonolithIC3D-HR10con3_Assignment_Brian_s#page1.tif source=MonolithIC3D-HR10con3_Assignment_Deepaks#page1.tif											

OP \$40.00 13864243

ASSIGNMENT

Whereas, I, **Zvi Or-Bach** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

Novel Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 13/864,243 and filed on April 17, 2013; and

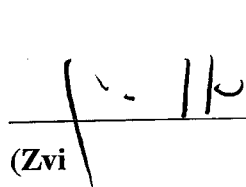
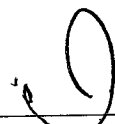

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged, I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 4.17.13

 (Zvi First Name	 Middle Initial	 Or-Bach) Last Name
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ASSIGNMENT

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s))**, residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

Novel Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 13/864,243 and filed on April 17, 2013; and

Whereas, **MonolithIC 3D™ Inc.**, a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").


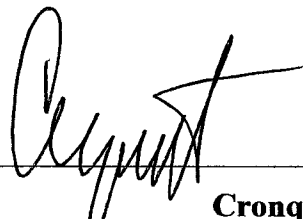
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Signed and Sealed:

INVENTOR:

DATE on 17 April 2013

	
(Brian	Cronquist)
First Name	Middle Initial Last Name

ASSIGNMENT

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

Novel Semiconductor Device and Structure

as described in U.S. Patent Application Serial No. 13/864,243 and filed on April 17, 2013; and

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

INVENTOR:

DATE on

10th Apr '13

(Deepak

First Name

Middle Initial

Sekar)

Last Name